C700 Smart Card Connectors: General Information

Contact Methods

**Landing Contacts**
With this contact method a moveable contact set will connect with the pads of the chip card upon insertion of the card.

The card plastic surface is not scratched and high mating cycles can be achieved.

**Wiping Contacts**
The contact set is fixed. When the card is inserted, it wipes over the data contacts until they arrive at the card pads. Depending upon the card surface, wiping traces which do not influence the card function can occur after some insertion cycles.

The advantage of wiping contacts is that they clean the contact point with every mating cycle.

**Landing Card**
This method of contacting is based on a fixed contact set. The chip card is lowered during its insertion.

The contact areas of the chip card land smoothly on the reading contacts which results in the possibility of a high number of mating cycles.

In addition this system makes sure that with each insertion the contact surfaces are cleaned.
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**SIMLOCK®**

In cases where chip cards with the dimensions of a full size ISO 7816 are too large, the SIMLOCK® comes into use. With its latching cover for the insertion of the smaller SIM card it offers a safe contact interface even in mobile usage.

Due to the locking system the user does not have to consider tolerances or card guiding.

The design and packaging of the Amphenol SIMLOCK® allows manual and automatic pick and placement prior to surface mount soldering.

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**SIMBLOCK®**

These Smart Card Connectors, due to their minimal space requirement and low height are the ideal components for many space restricted applications, from handsets to the electronic purse. The connector is suitable for standard chip cards per ISO 7816 as well as for plug-in SIM cards.

The SMT terminals and packaging for automatic handling allow the use of pick and place robots and modern surface solder technologies.

Positioning and support of the chip card has to be ensured by the user.